Nch 650V 20A Power MOSFET

V _{DSS}	650V
R _{DS(on)} (Max.)	0.205Ω
I _D	±20A
P _D	231W

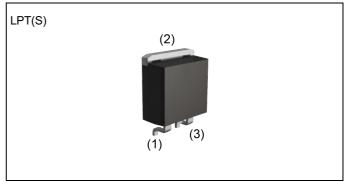
Features

- 1) Low on-resistance
- 2) Ultra fast switching speed
- 3) Parallel use is easy
- 4) Pb-free plating; RoHS compliant

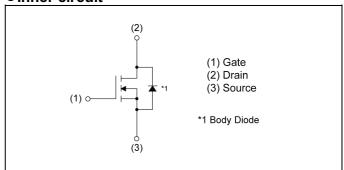
Application

Switching

Outline



•Inner circuit



Packaging specifications

Packing	Embossed Tape
Packing code	TL
Marking	R6520KNJ
Basic ordering unit (pcs)	1000

● **Absolute maximum ratings** (T_a = 25°C ,unless otherwise specified)

Parameter	Symbol	Value	Unit	
Drain - Source voltage		V_{DSS}	650	V
Continuous drain current (T _c = 25	5°C)	I _D *1	±20	Α
Pulsed drain current	l _{DP} *2	±60	А	
0.1.0	static	V _{GSS}	±20	V
Gate - Source voltage	AC(f>1Hz)		±30	V
Avalanche current, single pulse	<u>, </u>	I _{AS}	3.4	А
Avalanche energy, single pulse		E _{AS} *3	444	mJ
Power dissipation $(T_c = 25^{\circ}C)$	P _D	231	W	
Junction temperature	T _j	150	°C	
Operating junction and storage te	mperature range	T _{stg}	-55 to +150	°C

●Thermal resistance

Downwortow	Cymah al	Values			1.124
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R _{thJC} *4	-	-	0.54	°C/W
Thermal resistance, junction - ambient	R _{thJA} *5	-	-	80	°C/W
Soldering temperature, wavesoldering for 10s	T _{sold}	-	-	265	°C

● Electrical characteristics (T_a = 25°C)

Parameter	Cumb al	Conditions	Values			Unit	
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Offic	
Drain - Source breakdown voltage		$V_{GS} = 0V$, $I_D = 1mA$	650	-	-	V	
		$V_{DS} = 650V, V_{GS} = 0V$					
Zero gate voltage drain current	I _{DSS}	$T_j = 25^{\circ}C$	-	-	100	μΑ	
		$T_j = 125^{\circ}C$	1	-	1000		
Gate - Source leakage current	I _{GSS}	V_{GS} = ±20V, V_{DS} = 0V	1	-	±100	nA	
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_{D} = 630 \mu A$	3	-	5	V	
		V _{GS} = 10V, I _D = 9.5A					
Static drain - source on - state resistance	R _{DS(on)} *6	$T_j = 25^{\circ}C$	-	0.185	0.205	Ω	
		$T_j = 125^{\circ}C$	-	-	-		
Gate resistance	R_{G}	f = 1MHz, open drain	-	2.4	-	Ω	

● Electrical characteristics (T_a = 25°C)

Davamatar	Cymah al	Conditions		Unit		
Parameter	Parameter Symbol		Min.	Тур.	Max.	Unit
Input capacitance	C _{iss}	V _{GS} = 0V	-	1550	-	
Output capacitance	C _{oss}	V _{DS} = 25V	-	1450	-	pF
Reverse transfer capacitance C _{rss}		f = 1MHz	-	45	-	
Turn - on delay time	t _{d(on)} *6	$V_{DD} \simeq 300V$, $V_{GS} = 10V$	-	30	-	
Rise time	t _r *6	I _D = 10A	-	50	-	no
urn - off delay time $t_{d(off)}^{*6}$		$R_L \simeq 30\Omega$	-	75	-	ns
Fall time	t _f *6	$R_G = 10\Omega$	-	30	-	

● Gate charge characteristics (T_a = 25°C)

Darameter	Cymah al	Conditions		Values	Unit	
Parameter	Parameter Symbol		Min.	Тур.		Max.
Total gate charge	Q_g^{*6}	V _{DD} ≈ 300V	-	40	-	
Gate - Source charge	Q _{gs} *6	I _D = 20A	-	10	-	nC
Gate - Drain charge	Q _{gd} *6	V _{GS} = 10V	-	17	-	
Gate plateau voltage V _(plateau)		V _{DD} ≈ 300V, I _D = 20A	-	6.8	-	V

^{*1} Limited only by maximum channel temperature allowed.

^{*2} Pw ≤ 10µs, Duty cycle ≤ 1%

^{*3} L \doteqdot 70mH, V_{DD}=50V, R_G=25 Ω , STARTING T_i=25 $^{\circ}$ C

^{*4} T_C=25°C

^{*5} Mounted on an epoxy PCB FR4 (25mm x 27mm x 0.8mm)

^{*6} Pulsed

● Body diode electrical characteristics (Source-Drain) (T_a = 25°C)

Parameter	Symbol	Conditions		Unit			
- Farameter	Symbol	Conditions	Min.	Тур.	Max.	Offic	
Source current	I _S *1	T _C = 25°C	-	-	20	Α	
Pulsed source current	I _{SP} *2	1C - 23 C	-	-	60	Α	
Source-Drain voltage	V _{SD} *6	$V_{GS} = 0V, I_{S} = 20A$	-	-	1.5	V	
Reverse recovery time	t _{rr} *6		-	500	-	ns	
Reverse recovery charge	Q _{rr} *6	I _S = 20A di/dt = 100A/μs	-	8	-	μC	
Peak reverse recovery current	_{rr} *6		-	32	-	Α	

Fig.1 Power Dissipation Derating Curve

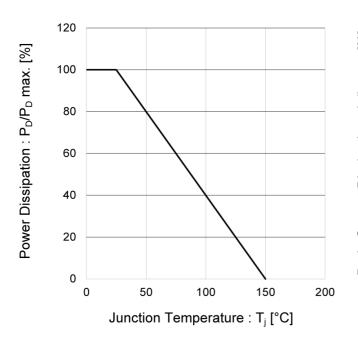


Fig.2 Drain Current Derating Curve

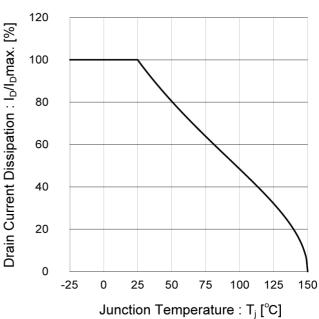


Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

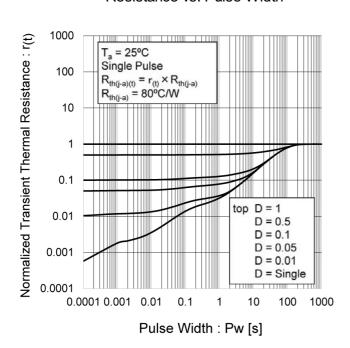


Fig.4 Maximum Safe Operating Area

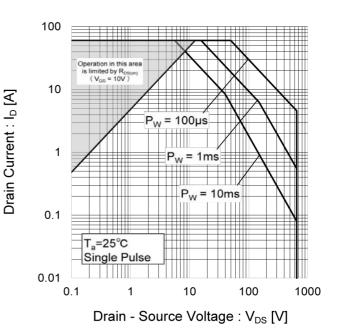


Fig.5 Avalanche Energy DeratingCurve vs. Junction Temperature

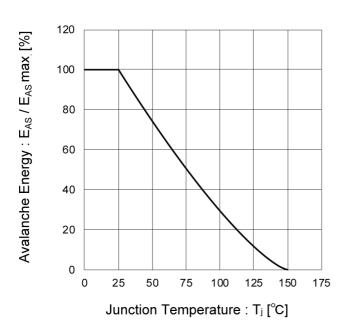


Fig.6 Breakdown Voltage vs. Junction Temperature

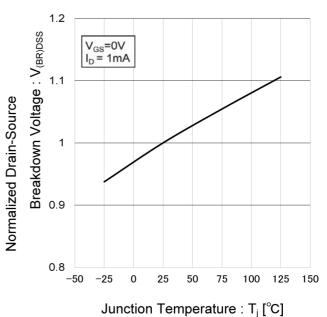


Fig.7 Typical Output Characteristics(I)

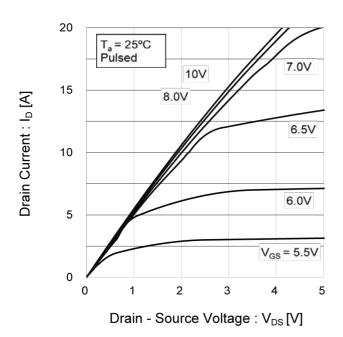
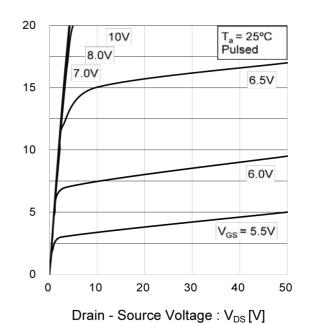


Fig.8 Typical Output Characteristics(II)



Drain Current : I_D [A]

Fig.9 Typical Transfer Characteristics

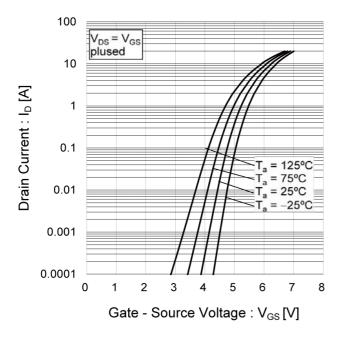


Fig.10 Normalized Gate Threshold .

Voltage vs Junction Temperature

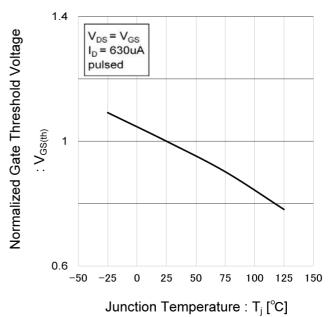


Fig.11 Static Drain - Source On - State Resistance vs. Drain Current

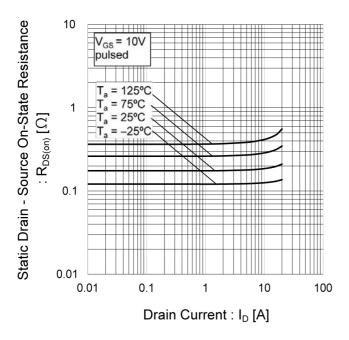


Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

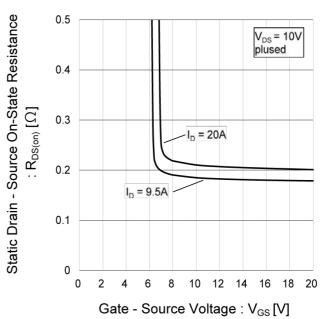


Fig.13 Normalized Static Drain - Source On - State Resistance vs. Junction Temperature

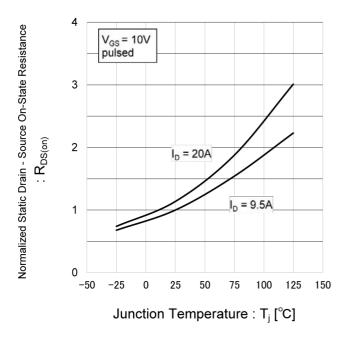
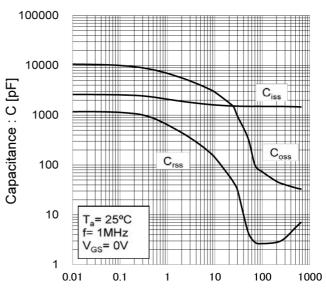


Fig.14 Typical Capacitance vs.

Drain - Source Voltage



Drain - Source Voltage: V_{DS}[V]

Fig.15 Switching Characteristics

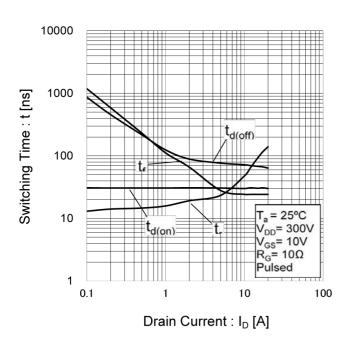
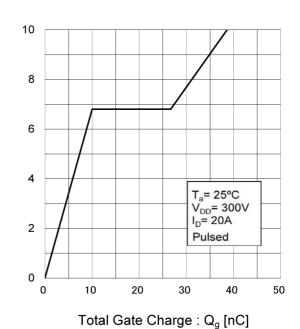


Fig.16 Typical Gate Charge



Gate - Source Voltage : V_{GS} [V]

Fig.17 Source Current vs. Source - Drain Voltage

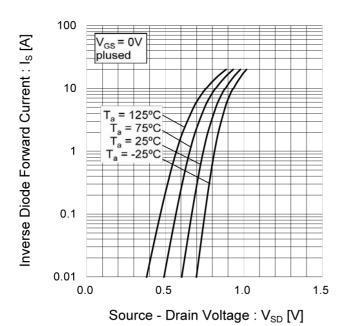
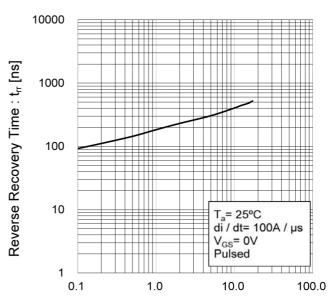


Fig.18 Reverse Recovery Time vs.
Inverse Diode Forward Current



Inverse Diode Forward Current : I_S [A]

Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

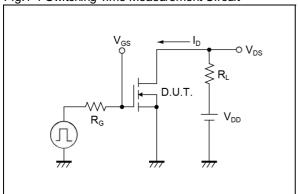


Fig.2-1 Gate Charge Measurement Circuit

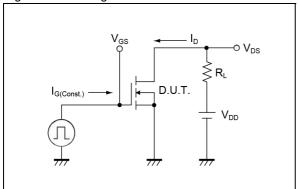


Fig.3-1 Avalanche Measurement Circuit

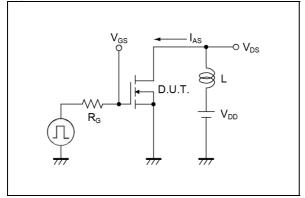


Fig.4-1 trr Measurement Circuit

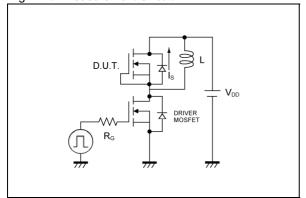


Fig.1-2 Switching Waveforms

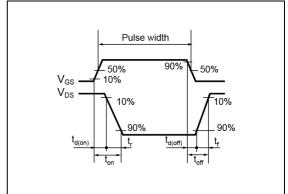


Fig.2-2 Gate Charge Waveform

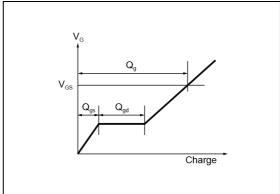


Fig.3-2 Avalanche Waveform

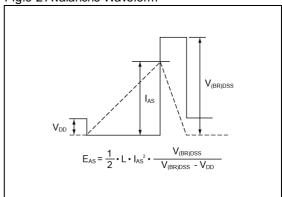
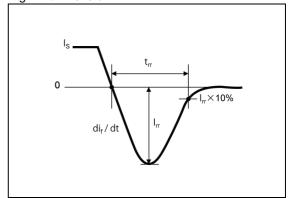
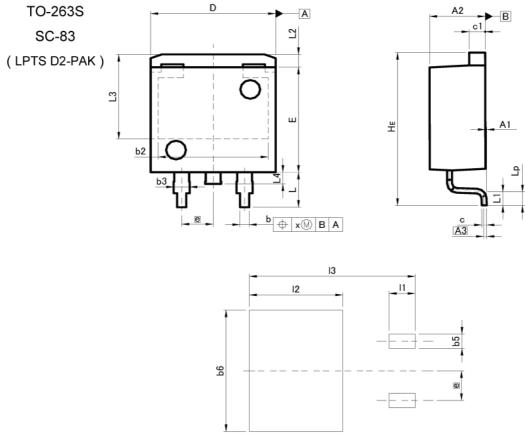


Fig.4-2 trr Waveform



Dimensions



Pattern of terminal position areas [Not a pattern of soldering pads]

DIM	MILIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
A1	0.00	0.30	0.000	0.012
A2	4.30	4.70	0.169	0.185
A3	0.:		0.0	
b	0.68	0.98	0.027	0.039
b2	8.9			50
b3	1.14	1.44	0.045	0.057
С	0.30	0.60	0.012	0.024
c1	1.10	1.50	0.043	0.059
D	9.80	10.40	0.386	0.409
E	8.80	9.20	0.346	0.362
е	2.	54	0.1	00
HE	12.80	13.40	0.504	0.528
L	2.70	3.30	0.106	0.130
L1	1.	20	0.047	
L2	1.	10	0.0	43
L3	7.25		0.2	85
L4	1,0	00	0.0	39
Lp	0.90	1.50	0.035	0.059
Х	770	0.25	-	0.010
	MILIMA		INC	1150

DIM	MILIM	MILIMETERS		HES
DIM	MIN	MAX	MIN	MAX
b5	Ξ.	1.23	-	0.049
b6	=(10.40		0.409
11	<u>12</u> 8	2.10	, 12	0.083 0.297
12	= X	7.55	1.00	0.297
13	_	13.40	-	0.528

Dimension in mm/inches



Notice

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CLASSIV	CLASSIII	CLASSⅢ	CLASSIII

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 - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

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- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
 may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
 exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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